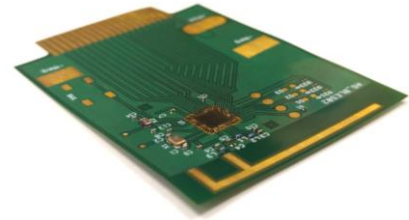


Overview

American Semiconductor's AS_DEVBLES02.kit FleX-BLE Development Kit provides a demonstration of Semiconductor-on-Polymer™ (SoP™) ultra-thin IC packaging technology for Bluetooth applications. This ultra-thin Bluetooth® Low Energy demonstrator is a development platform for your next generation BLE products. The kit utilizes a SoP packaged Nordic nRF51822 to demonstrate the thinnest BLE system-on-chip in the world and provide it in a fully functional chip-on-flex assembly. The FleX-BLE Development Kit provides an out-of-the-box demonstration of ultra-thin SoP IC packaging, chip-on-flex assembly, and supports developing, programming and demonstrating custom ultra-thin Bluetooth systems. The low-profile systems are ideal for conformal (to a minimum radius of 20mm) or in-mold applications.

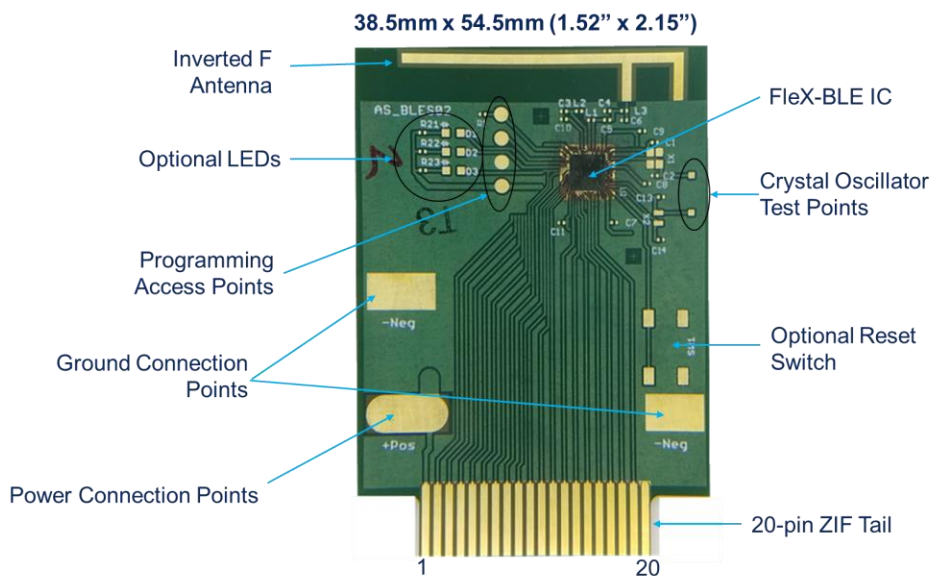


FleX-BLE Development Kit
AS_DEVBLES02.kit

FleX-BLE FHE Systems

Each FleX-BLE Development Kit is only 38.5 x 54.5mm and includes:

- AS_NRF51822P.fxd FleX-BLE ultra-thin, flexible silicon IC
- Multi-layer copper on 75um thick (3mil) polyimide flexible circuit board
- Digital and analog I/O pins for sensor system and application development
- 2-wire programming interface supports FleX-BLE chip firmware customization
- Zero Insertion Force tail for easy access to digital I/O, analog inputs, and programming pins



FleX-BLE Development Kit
AS_DEVBLES02.kit



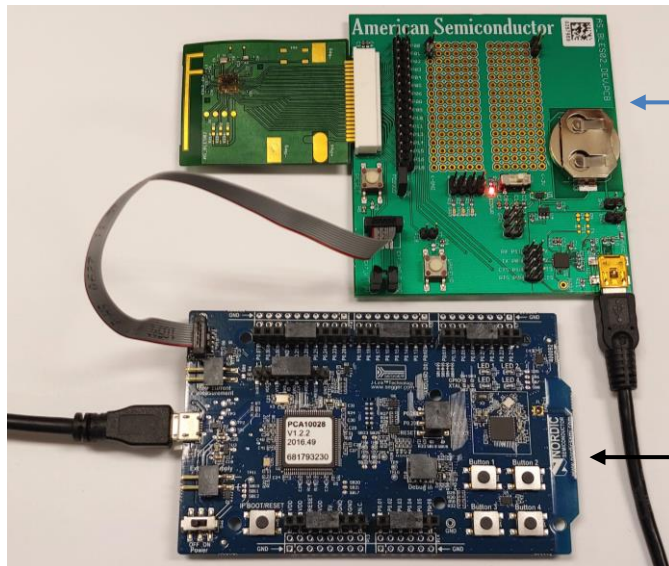
Development Support

Basic FleX-BLE FHE firmware and Android smartphone apps are provided to support initial demonstrations that can serve as a basis for user custom code and development.

FleX-BLE Programming Transition Printed Circuit Board (BLE PCB Assembly)

A FleX-BLE Programming Transition Circuit Board Assembly **can be purchased separately** to simplify code development and programming of the FleX-BLE Dev Kits. This Programming Transition Circuit Board integrates FleX-BLE Dev Kits with Nordic Semiconductor’s standard nRF51 development kit. The Programming Transition Circuit Board supports connection to the development hardware already available from Nordic Semiconductor. The Programming Transition Circuit Board Assembly features include:

- Debug port that connects to the Nordic PCB Debug out with fine-pitch (25 mil) ribbon cable
- A breakout panel for user connections to analog sensors or digital comm
- Analog and GPIO connections to the FleX-BLE Kit FHE system connect through the ZIF-20 connector to the Breakout Panel.
- A USB connector with FTDI interface support, battery mount, and power connection points that enable non-programming use of the Transition Board independent of the Nordic PCB.
- Reset and wakeup buttons
- User programmable LEDs



FleX-BLE Programming Transition
Printed Circuit Board Assembly
AS_DEVBLES02.asb

Nordic Semiconductor Dev Kit
for nRF51 Series
**Sold by Nordic Semi and
Distributors**

Ordering Information

Part Number	Description
AS_DEVBLES02.kit	FleX-BLE Basic Development Kit – Flexible Hybrid Electronics (BLE FHE System)
AS_DEVBLES02.asb	FleX-BLE Programming Transition Printed Circuit Board (BLE PCB Assembly)
AS_DEVBLES02A.kit	FleX-BLE Advanced Dev Kit with BLE FHE System and BLE PCB Assembly

Contact Info

For more information or to purchase FleX products, please contact us at:

Email: sales@americansemi.com

Phone: 208.336.2773

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